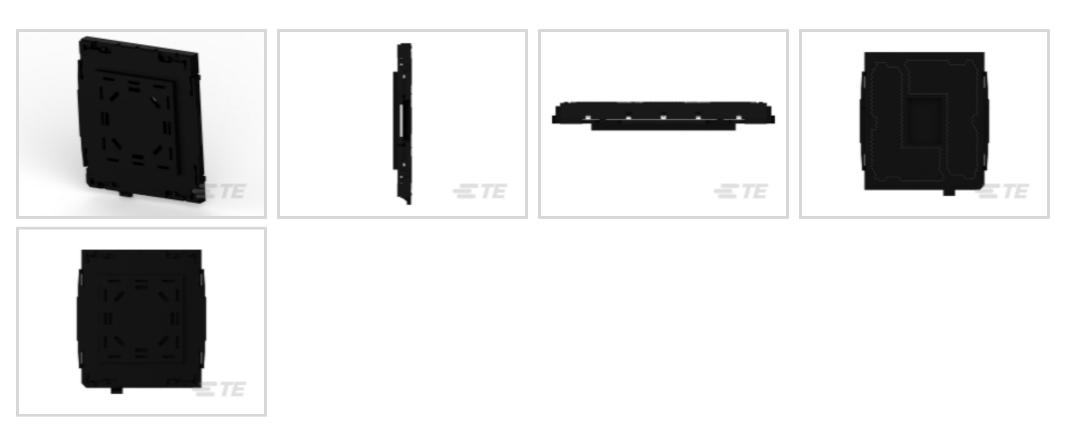
2174988-2 - ACTIVE

TE Internal #: 2174988-2 LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold, Contact Mating Area Plating Material Thickness 30 µin, 1.02mm [. 04in] Centerline

View on TE.com >



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 2011 SOCKETS



IC Socket Type: LGA 2011

Connector System: Board-to-Board

Number of Positions: 2011

Contact Mating Area Plating Material: Gold

Contact Mating Area Plating Material Thickness: [30 µin]

All LGA 2011 SOCKETS (6)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket
Configuration Features	
Number of Positions	2011
Grid Spacing	1.016 x .8814 mm[.040 x .0347 in]
Body Features	
Frame Style	Square
Plating Material	Gold
Plating Thickness	30 µin
Contact Features	
Contact Base Material	Copper Alloy
IC Socket Type	LGA 2011

C For support call+1 800 522 6752

2174988-2

LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold, Contact Mating Area Plating Material Thickness 30 µin, 1.02mm [.04in] Centerline



Contact Mating Area Plating Material	Gold
	30 µin
Contact Current Rating (Max)	.5 A
Mechanical Attachment	
Heat Sink Attachment	Without
PCB Mounting Style	Surface Mount Solder Ball
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.02 mm[.04 in]
Housing Material	High Temperature Thermoplastic
Housing Color	Black
Usage Conditions	
Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0

Packaging Features

Tray Color	Blue
Packaging Method	Tray
Other	
Comment	Lead-Free Solderball
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	

C For support call+1 800 522 6752

07/30/2021 11:54AM | Page 2

Candidate List Declared Against: JAN 2021

Does not contain REACH SVHC

(211)

2174988-2

LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold, Contact Mating Area Plating Material Thickness 30 µin, 1.02mm [.04in] Centerline



Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Customers Also Bought



Free Height Receptacle Conn: Board-Board, Vertical, 80, 0.8mm

IMP100S, H, V4P6C, LG, REW39, 5.5



TE Part #5-292228-4 MINI COMMON TERMINATION HEADERS



TE Part #2057404-1 IMP100S,R,RA2P10C,RG,39



TE Part #2291491-1 zSFP+ Stacked Cage Assembly: EMI Spring



TE Part #2007855-3 IMP100S,H,V5P10C,UG,REW39,5.5



Documents

2174988-2

LGA Sockets, LGA 2011, Board-to-Board, 2011 Position, Gold, Contact Mating Area Plating Material Thickness 30 µin, 1.02mm [.04in] Centerline



Product Drawings SOCKET ASSY LGA2011-1 0.76um Au

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2174988-2_D.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2174988-2_D.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2174988-2_D.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

English

Product Environmental Compliance Product Compliance

English

Product Compliance

English